

**IN THE CLAIMS;**

Please amend the claims as follows:

1. **(Canceled).**

2. **(Canceled).**

3. **(Currently Amended)** A process for preventing dust generation of a wafer storage case comprising the steps of:

coating a surface of the wafer storage case of synthetic resin housing wafers with a coating agent;

drying the wafer storage case coated with the coating agent;

cleaning the dried wafer storage case and removing particles on a surface of a coating layer using pure water such that a the coating layer of the coating agent remains across the surface of the wafer storage case; and

drying the cleaned wafer storage case,

wherein dust generation from the surface of the wafer storage case is prevented by the coating layer of the coating agent.

4. **(Currently Amended)** A process for preventing dust generation of a wafer storage case comprising ~~a step~~ the steps of:

coating a surface of the wafer storage case of synthetic resin housing wafers with a coating agent;

cleaning the wafer storage case and removing particles on a surface of a coating layer using pure water such that a the coating layer of the coating agent remains across the surface of the wafer storage case; and

drying the cleaned wafer storage case,

wherein dust generation from the surface of the wafer storage case is prevented by the coating layer of the coating agent.

5. **(Original)** The process for preventing dust generation of a wafer storage case according to claim 4, wherein the pure water used in the step of cleaning with the pure water such that the coating layer of the coating agent remains across the surface of the wafer storage case is pure water with a low specific resistance.

6. **(Original)** The process for preventing dust generation of a wafer storage case according to claim 5, wherein the pure water with a low specific resistance has a specific resistance of 10 MΩ·cm or less.

7. **(Original)** The process for preventing dust generation of a wafer storage case according to any of claims 3 to 6, wherein by immersing the wafer storage case in an aqueous solution of a coating agent, the surface of the wafer storage case is coated with the coating agent.

8. **(Previously Presented)** The process for preventing dust generation of a wafer storage case according to any of claims 3 to 6, wherein the wafer storage case to be coated with the coating agent is a cleaned wafer storage case.

9. **(Original)** The process for preventing dust generation of a wafer storage case according to claim 8, wherein the cleaned wafer storage case is a wafer storage case cleaned with surfactant cleaning and pure water cleaning.

10. **(Previously Presented)** The process for preventing dust generation of a wafer storage case according to any of claims 3 to 6, wherein the coating agent is a surfactant.

11. **(Canceled).**

12. **(Previously Presented)** A wafer storing method comprising the steps of:
- preparing wafers; and
  - housing the wafers in a wafer storage case treated by a process for preventing dust generation of a wafer storage case according to any of claims 3 to 6.